

STRUCTURES FOR IMPLEMENTING INTEGRATED CONDUCTOR AND CAPACITOR IN SMD PACKAGING

Abstract of the Disclosure

5 Structures are provided for implementing an integrated conductor and capacitor in a surface mounted device (SMD) package. A first pair and a second pair of contacts contained within the SMD package respectively are provided in mating engagement with a first pair and a second pair of corresponding SMD package contacts. A conductor extends between the first pair of contacts, contained within the SMD package. A capacitor is
10 defined between the second pair of contacts, contained within the SMD package. An additional one or pair of integral capacitors optionally is provided for providing additional capacitance to ground to decouple common mode noise from the power planes.